KN PACKAGE

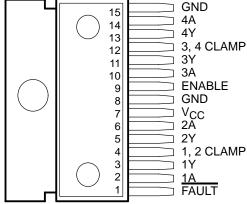
SLIS007A - D3299, AUGUST 1989 - REVISED MAY 1993

- 1-A Current Capability Per Channel
- 45-V Inductive Switching Voltage Capability
- Current Sink Inputs Compatible With TTL or CMOS Devices
- Output Clamp Diodes for Inductive Transient Protection
- Independent Thermal Shutdown Protection
- Overvoltage Shutdown Protection
- Independent Channel Current Limit
- Error Sensing
- Extended Temperature Range of -40°C to 125°C

description

The TPIC2404 is a monolithic high-voltage high-current quadruple low-side switch especially

(TOP VIEW)



The tab is electrically connected to the GND pins.

designed for driving from low-level logic to peripheral loads such as relays, solenoids, motors, lamps, and other high-voltage high-current loads. The high-efficiency power switch is optimized for applications where a very rugged power switch is required. The device tolerates power supply transients and reverse battery conditions up to 13 V.

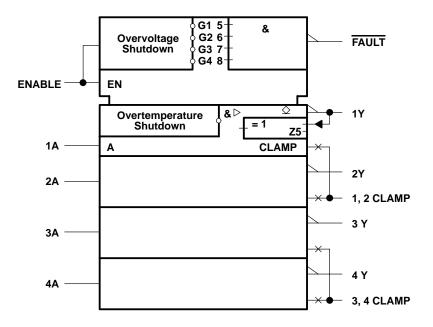
The TPIC2404 features four inverting open-collector outputs controlled by a common-enable input. When ENABLE is low, the outputs are disabled. An error-sensing circuit monitors load and device faults. When an error is sensed, the $\overline{\mathsf{FAULT}}$ output goes to a low state. In addition, the device features on-board V_{CC} overvoltage and thermal overload protection circuits, and the outputs are current limit protected.

FUNCTION TABLE

	INPUT	S	ΟU	TPUTS
	ENABLE	Α	Υ	FAULT
	Н	Н	L	Н
Normal operation	Н	L	Н	Н
	L	X	Н	Н
Open load	Н	L	L	L
Openioad	Н	Н	L	Н
Short to GND	Н	L	L	L
SHOIL TO GIVD	Н	Н	L	Н
Over reltade about deven	Н	Н	Н	L
Overvoltage shutdown	Н	L	Н	Н
Thermal shutdown	Н	Н	Н	L
mermai snutdown	Н	L	Н	Н
Short to VCC	Н	Н	Н	L
Short to ACC	Н	L	Н	Н

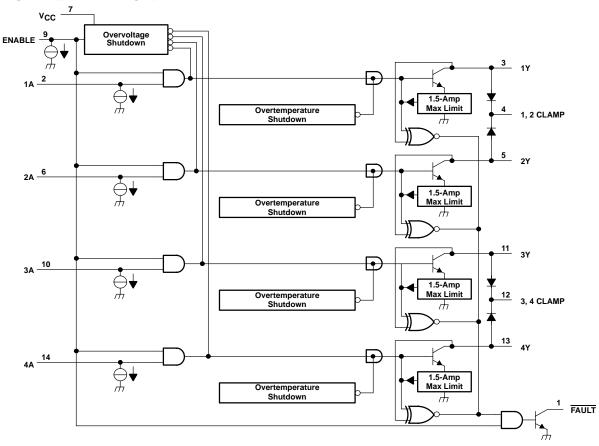
H = high level, L = low level, X = irrelevant

logic symbol[†]

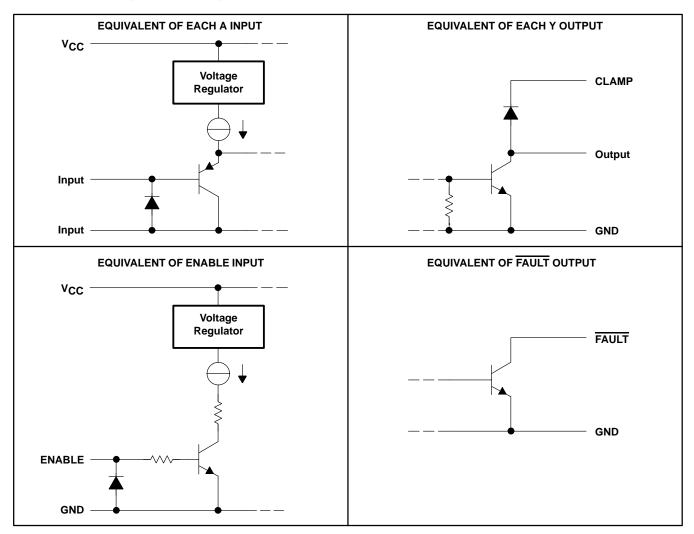


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



schematics of inputs and outputs

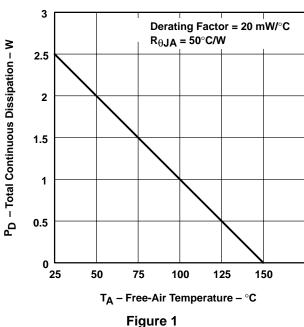


absolute maximum ratings over operating temperature range (unless otherwise noted)

Supply voltage range, V _{CC} (see Note 1)	13 V to 24 V
Input voltage range, V _I	0.6 V to 7 V
Output voltage range, VO (see Note 2)	0.6 V to 45 V
Output sustaining voltage, V _{O(sust)}	45 V
Continuous output sink current (repetitive, t _w < 8 ms), I _{OL} (see Note 3)	1.5 A
Output clamp-diode voltage, V _{OK}	45 V
Continuous total dissipation at (or below) 25°C case temperature (see Note 4)	50 W
Operating case or virtual junction temperature range	. −55°C to 150°C
Storage temperature range	. −65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

- NOTES: 1. All voltage values are with respect to network GND.
 - 2. For a fault condition to be valid, the output voltage needs to be a minimum of 7 V.
 - 3. Output sink current is limited by the overcurrent limit.
 - 4. For operation above 25°C free-air or case temperature, refer to Figures 1 and 2. To avoid exceeding the design maximum virtual junction temperature, these ratings should not be exceeded. Due to variations in individual device electrical characteristics and thermal resistance, the built-in thermal overload protection can be activated at power levels slightly above or below rated dissipation.

FREE-AIR TEMPERATURE DISSIPATION DERATING CURVE



CASE TEMPERATURE DISSIPATION DERATING CURVE

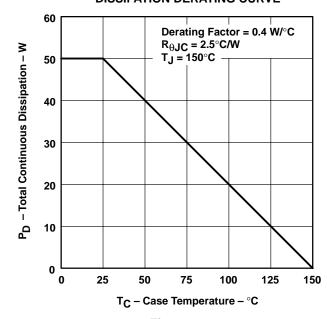


Figure 2

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}	9	12	16	V
High-level input voltage, VIH	2		5.5	V
Low-level input voltage, V _{IL}	-0.3†		0.8	V
Peak output voltage from external inductive kickback			45	V
Continuous output sink current			1	Α
FAULT output sink current			75	μΑ
Operating free-air temperature, TA	-40		125	°C

[†] The algebraic convention, in which the least positive (most negative) value is designated as minimum, is used in this data sheet for logic voltage levels.

electrical characteristics over recommended ranges of operating free-air temperature and supply voltages (unless otherwise noted)

PARAMETER		TEST	TEST CONDITIONS		TYP‡	MAX	UNIT	
			V _O = 12 V,	ENABLE low		15	100	μΑ
IO(off) Off-state output current	Off-state output current		$V_0 = 45 V$	ENABLE high		0.6	2	mA
· <i>'</i>		$V_0 = 12 V$	ENABLE high	200	400	600	μΑ	
Iμ	Low-level input current		V _I = 0 to 0.8 V		-10	25	40	μΑ
ΊΗ	High-level input current	A inputs			10	25	60	μΑ
		ENABLE				0.2	1	mA
V _{OL} Low-level output voltage			I _{OL} = 100 mA			0.1	0.15	
		$I_{OL} = 500 \text{ mA}$			0.3	0.55	V	
		I _{OL} = 1 A			0.8	1.3		
		FAULT output,	I _{OL} = 30 μA		0.2	0.4		
loL	Low-level output current		FAULT output,	V _{OL} = 1 V to 5.5 V	50	90	125	μΑ
I _{R(K)}	Clamp-diode reverse currer	nt	$V_r = 50 \text{ V},$	V _O = 0			100	μΑ
V _{F(K)} Clamp-diode forward voltage		I _f = 1 A				2		
	Clamp-diode forward voltage		I _f = 1.5 A				2.5	V
ICC	Supply current		Outputs off,	ENABLE low			0.25	mA
			Outputs on,	T _A = -40°C			120	
			Outputs on,	T _A = 25°C to 125°C			100	

operating characteristics over recommended operating free-air temperature and supply voltages (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP‡	MAX	UNIT
High-level output sense voltage threshold				7	V
Low-level output sense voltage threshold		3			V
Overvoltage shutdown		25.5		31	V
Overvoltage shutdown hysteresis			0.25		V
Overcurrent limiting	T _A = -40°C			1.85	^
	$T_A = 25^{\circ}C$ to $125^{\circ}C$		1.2	1.5	Α
Thermal shutdown			155		°C
Thermal shutdown hysteresis			15		°C
Turn-on time			8		μs
Turn-off time			8		μs

[‡] All typical values are at $V_{CC} = 12 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



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